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# Table of Contents

**Volume 7  Number 5  May 2017**

**Copper Adsorption from Wasterwater Using Bone Charcoal**  
S. Ghrab, M. Benzina, S. D. Lambert  
--- 139

**Photophysical, Electrochemical and Photovoltaic Properties of Porphyrin-Based Dye Sensitized Solar Cell**  
--- 148

**Characteristics of a Silicon Wafer <111> and <004> after Planting Nitrogen**  
M. Simiari, R. R. Mogaddam  
--- 173

**Model of the Pulsing Atom**  
H. Ehrlich  
--- 188

**The Effect of Nitrogen Gas Flow Rate on the Cr-Containing DLC (Diamond-Like Carbon) Coating by AEGD Hybrid-CVD Coating Process**  
--- 198

**Metal-Insulator Transition of Peierls Type in Quasi-One-Dimensional Crystals of TTT$_2$I$_3$**  
S. Andronic, A. Casian  
--- 212
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